

RELIABILITY REPORT  
FOR  
MAX3625CUG+  
PLASTIC ENCAPSULATED DEVICES

December 4, 2008

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

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## Conclusion

The MAX3625CUG+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

## Table of Contents

<b>I. ....Device Description</b>	<b>V. ....Quality Assurance Information</b>
<b>II. ....Manufacturing Information</b>	<b>VI. ....Reliability Evaluation</b>
<b>III. ....Packaging Information</b>	<b>IV. ....Die Information</b>
<b>.....Attachments</b>	

### I. Device Description

#### A. General

The MAX3625 is a low-jitter precision clock generator optimized for networking applications. The device integrates a crystal oscillator and a phase-locked loop (PLL) clock multiplier to generate high-frequency clock outputs for Ethernet, 10G Fibre Channel, and other networking applications. Maxim's proprietary PLL design features ultra-low jitter and excellent power-supply noise rejection, minimizing design risk for network equipment. The MAX3625 has three LVPECL outputs. Selectable output dividers and a selectable feedback divider allow a range of output frequencies.

## II. Manufacturing Information

A. Description/Function:	Low-Jitter, Precision Clock Generator with Three Outputs
B. Process:	MB3H
C. Number of Device Transistors:	10,670
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Thailand, Malaysia
F. Date of Initial Production:	October 22, 2007

## III. Packaging Information

A. Package Type:	24-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2572
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	82°C/W
K. Single Layer Theta Jc:	15°C/W
L. Multi Layer Theta Ja:	72°C/W
M. Multi Layer Theta Jc:	13°C/W

## IV. Die Information

A. Dimensions:	82 X 82 mils
B. Passivation:	BCB/Si <sub>3</sub> N <sub>4</sub> (Silicon nitride)
C. Interconnect:	Aluminum/Copper
D. Backside Metallization:	None
E. Minimum Metal Width:	0.23 microns (as drawn)
F. Minimum Metal Spacing:	0.23 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	Silicon Dioxide
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 150C biased (static) life test are pending. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.4 \times 10^{-9}$$
$$\lambda = 22.4 \text{ F.I.T. (60\% confidence level @ 25}^\circ\text{C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the MB3H Process results in a FIT Rate of 0.7 @ 25C and 11.5 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The HD86 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX3625CUG+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 150C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data